

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): R. Shane Fazzio

Serial No.: 10/807,417

Examiner: Monica Lewis

Filing Date: March 23, 2004

Group Art Unit: 2822

Title: Microcap Wafer Bonding Apparatus

COMMISSIONER FOR PATENTS
P.O. Box 1460
Alexandria VA 22313-1460

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- ☒ Response/Amendment ☒ Petition to extend time to respond
☐ New fee as calculated below ☐ Supplemental Declaration
☐ No additional fee (Address envelope to "Mail Stop Amendments")
☐ Other: Response to Notice of Non-Compliant Amendment (Fee \$ _____)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS		MINUS		= 0	X 50	\$ 0
INDEP. CLAIMS		MINUS		= 0	X 210	\$ 0
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ 370	\$ 0
EXTENSION FEE	1 ST MONTH 120.00 <input checked="" type="checkbox"/>	2 ND MONTH 460.00 <input type="checkbox"/>	3 RD MONTH 1050.00 <input type="checkbox"/>	4 TH MONTH 1640.00 <input type="checkbox"/>		\$ 120
					OTHER FEES	\$ 0
					TOTAL ADDITIONAL FEE FOR THIS AMENDMENT	\$ 120

Charge \$120 to Deposit Account 50-3718. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-3718 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 50-3718 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this transmittal letter is enclosed.

Respectfully submitted,

R. Shane Fazzio

By 

Thomas F. Woods
Attorney/Agent for Applicant(s)

I hereby certify that this paper is being electronically transmitted to the Commissioner for Patents on the date shown below

Date of Transmission: April 21, 2008

Typed Name: Thomas F. Woods

Signature: 

Reg. No. 36,726

Date: April 21, 2008

Telephone No. (303) 823-6560

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. Shane Fazio

Examiner Name: Monica Lewis

Serial No.: 10/807,417

Group Art Unit: 2822

Filed: March 23, 2004

Attorney Docket No.: 10030899-1

Confirmation No.: 3854

Title: Microcap Wafer Bonding Apparatus

RESPONSE AND AMENDMENT

Commissioner for Patents
P.O. Box 1450
Arlington, VA 22313-1450

Sir:

In response to the Office Action dated December 20, 2007, Applicants respectfully request entry of the amendments set forth herein, and allowance of the above-identified patent application as amended herein:

DATE OF DEPOSIT: April 21, 2008

CERTIFICATE OF ELECTRONIC DEPOSIT: I hereby certify that all paper(s) described herein are being filed electronically with the United States Patent and Trademark Office on the date indicated above and addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature: Thomas F. Woods

Printed Name: Thomas F. Woods, Reg. No. 36,726